

SSC8L40PN6

N-Channel Enhancement Mode MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	ID
40V	+20V	1.2mΩ@10V	222A
	<u> - 20 v</u>	1.8mΩ@4V5	2220

Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔVDS + Rg Tested!

Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

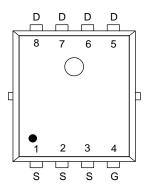
Ordering Information

Device	Package	Shipping
SSC8L40PN6	PDFN5X6-8L	5000/Reel

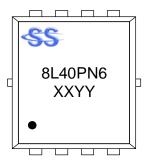
> Pin Configuration



PDFN5X6-8L



Pin Configuration (Top View)



Marking

(XXYY: Internal Traceability Code)



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V _{DSS}	Drain-to-Source Volta	Drain-to-Source Voltage		V
V _{GSS}	Gate-to-Source Volta	ge	±20	V
	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	222	^	
ID	Continuous Drain Current	T _C =100℃	123	A
	Continuous Dunin Comment 2	T _A =25℃	36	^
IDSM	Continuous Drain Current ^a	T _A =70°C	26	Α
I _{DM}	Pulsed Drain Curren	t ^b	888	Α
	5 5	Tc=25°C	96	107
P _D	Power Dissipation •	age $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ Single Pulse Single Pulse erature	39	W
Б	David Divide the s	T _A =25℃	2.5	34/
P _{DSM}	Power Dissipation ^a	T _A =70°C	1.6	W
las	Avalanche Current ^b L=0.5mH Single Pulse		26	Α
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		169	mJ
TJ	Operation junction temperature		-55~150	°C
T _{STG}	Storage temperature ra	inge	-55~150	℃

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R _{θJA}	Junction-to-Ambient Thermal Resistance ^a	50	°C/W
$R_{ heta JC}$	Junction-to-Case Thermal Resistance	1.3	C/VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.1 www.sscsemi.com Analog Future



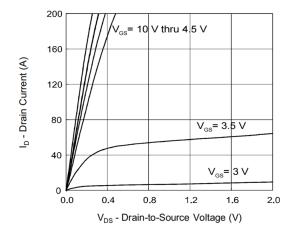


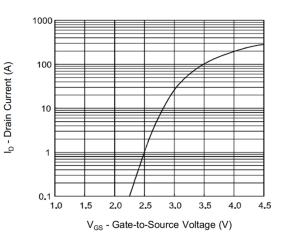
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250$ uA	1.4	1.8	2.4	٧
Drain-Source On-Resistance	D	$V_{GS} = 10V, I_D = 30A$ $V_{GS} = 4.5V, I_D = 20A$		1.2	1.7	mΩ
Drain-Source On-Resistance	KDS(on)			1.8	2.8	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	lgss	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A		0.76	1.4	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.2		Ω
Input Capacitance	Ciss	V - 00V V - 0V		4275		
Output Capacitance	Coss	$V_{DS} = 20V$, $V_{GS} = 0V$, $f = 1MHz$		1751		pF
Reverse Transfer Capacitance	C _{RSS}	T = TIVIHZ		136		
Total Gate Charge	Q _G	V 40V/V 00V		72		
Gate to Source Charge	Q _{GS}	V _{GS} = 10V, V _{DS} = 20V,		24		nC
Gate to Drain Charge	Q _{GD}	I _D = 20A		8		
Turn-on Delay Time	T _{D(ON)}			20		
Rise Time	Tr	V _{GS} = 10V, V _{DS} = 20V, R _L		63		
Turn-off Delay Time	T _{D(OFF)}	= 1Ω , $R_G = 3\Omega$		58		ns
Fall Time	T _f			16		
Diode Recovery Time	Trr	I _F =20A, di/dt=500A/us		58		ns
Diode Recovery Charge	Qrr	I _F =20A, di/dt=500A/us		67		nC



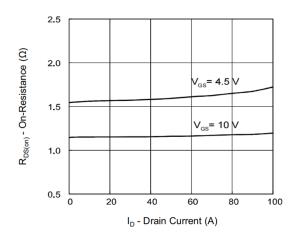
> Typical Performance Characteristics (T_A=25℃ unless otherwise noted)

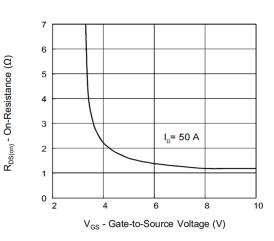




Output Characteristics

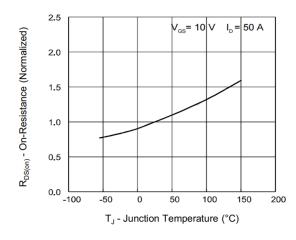
Transfer Characteristics

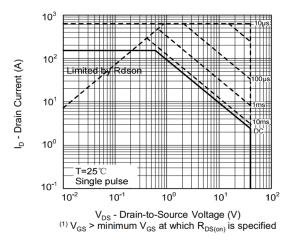




On-Resistance vs. Drain Current

On-Resistance vs. Gate-to-Source Voltage



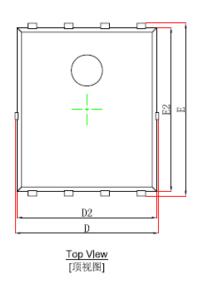


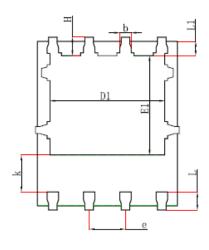
On-Resistance vs. Junction Temperature

Safe Operating Area

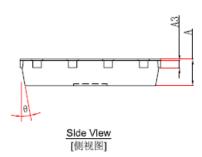


> Package Information





Bottom Vlew [背视图]



Package: PDNF5X6-8L

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
Α	0.900	1.000	0.035	0.039
A3	0.254REF		0.010	OREF
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270	1.270TYP		OTYP
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
Н	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°



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